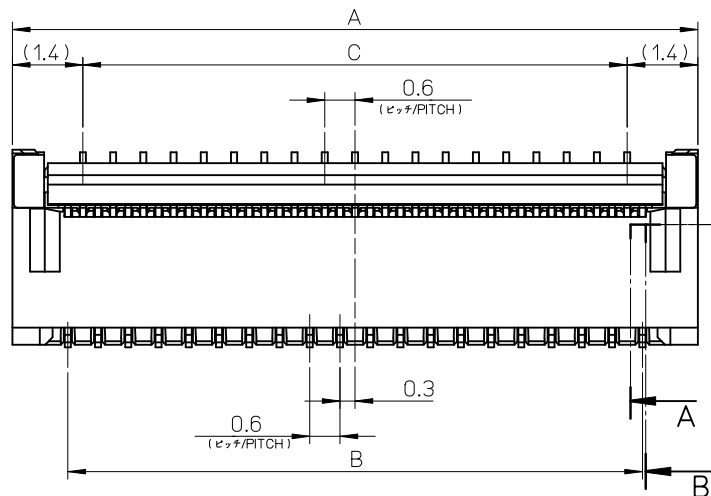
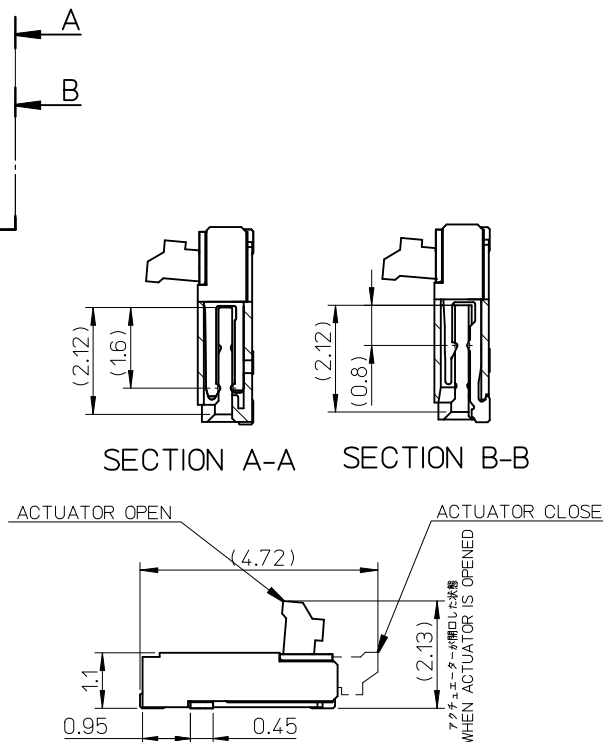


斜視図
SCALE 5:1



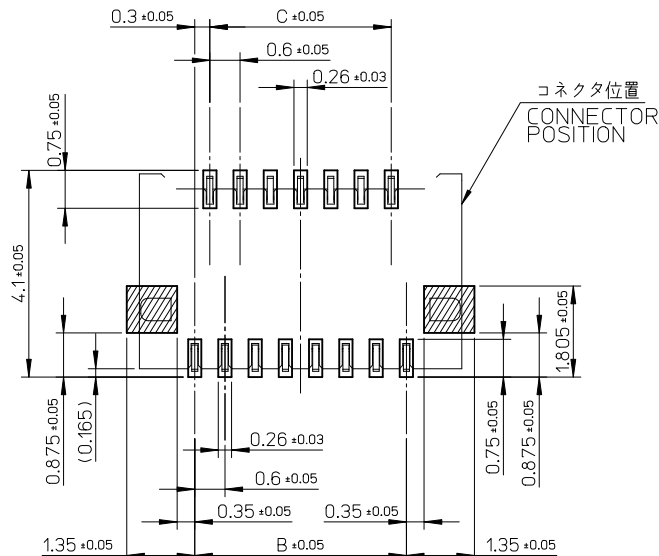
部品構成 PART COMPOSITION

- ハウジング: 液晶ポリマー (LCP)、
ガラス充填、UL94 V-0、ナチュラル (白)
HOUSING: LIQUID CRYSTAL POLYMER (LCP),
GLASS FILLED, UL94 V-0, NATURAL (WHITE)
- 奇数ターミナル: 銅合金
ODD TERMINAL: COPPER ALLOY
処理: ニッケル下地 部分金メッキ ニッケルストライプ(バリア)
FINISH: PARTLY GOLD
OVER NICKEL PLATING
NI STRIPE (BARRIER)
- 偶数ターミナル: 銅合金
EVEN TERMINAL: COPPER ALLOY
処理: ニッケル下地 部分金メッキ ニッケルストライプ(バリア)
FINISH: PARTLY GOLD
OVER NICKEL PLATING
NI STRIPE (BARRIER)
- アクチュエータ...材質: ポリアミド(PA) 黒色 UL94V-0
ACTUATOR MATERIAL: POLYAMIDE(PA)
BLACK UL94-V0
- ネイル...材質: 燐青銅
NAIL MATERIAL: PHOSPHOR BRONZE
処理: ニッケル下地すずめっき
FINISH: TIN OVER NICKEL PLATING
- ELV及びRoHS適合品
ELV & RoHS COMPLIANT

15.6	14.4	15	17.2	502350-5100	51
14.4	13.2	13.8	16.0	502350-4700	47
13.8	12.6	13.2	15.4	502350-4500	45
12.6	11.4	12	14.2	502350-4100	41
12	10.8	11.4	13.6	502350-3900	39
11.4	10.2	10.8	13	502350-3700	37
10.2	9	9.6	11.8	502350-3300	33
9.6	8.4	9	11.2	502350-3100	31
7.2	6	6.6	8.8	502350-2300	23
6	4.8	5.4	7.6	502350-1900	19
4.8	3.6	4.2	6.4	502350-1500	15
D	C	B	A	EMBOSSED PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS

CONNECTOR SERIES No. 502350-**09

REVISED EC NO.: J2011-0598 DRWN:SHIRATA 2010/10/19 CHK:K.TAKAHASHI 2010/10/19 APPR:KMORIKAWA 2010/10/25	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	T.HIRAYAMA	2009/01/05	TITLE 0.3 FPC CONN. E/O H=1.1 HOUSING ASSY WITH GUIDE				
		10 OVER 30 UNDER	± 0.25	CHECKED BY	DATE					
		30 OVER	± 0.3	N.MATSUURA	2009/01/05					
		APPROVED BY	DATE	MOLEX MOLEX INCORPORATED						
	KMORIKAWA	2010/10/25								
	ANGULAR	±3 °	MATERIAL NO.		DOCUMENT NO.		SHEET NO.			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-502350-001		1 OF 2				
REV			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						



参考基板レイアウト (マウント面)

P.C. BOARD PATTERN
DIM.(REF.)

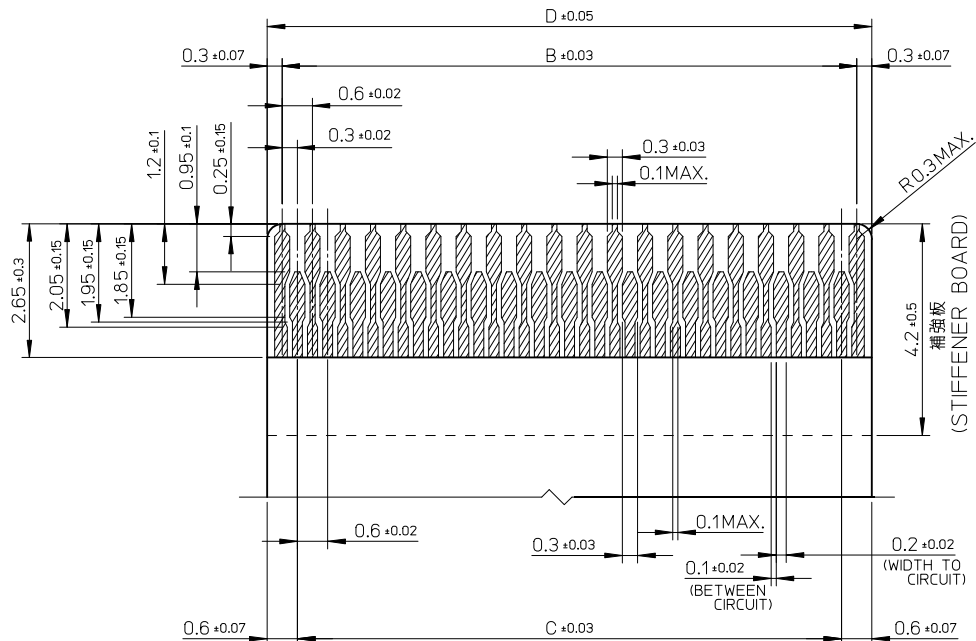
推奨メタルマスク厚さ : 0.1mm
RECOMMENDED METAL MASK THICKNESS : 0.1mm
推奨開口率 : 100%
APERTURE RATE : 100%

注記
NOTE

- 基板実装前にアクチュエータを操作しないで下さい。
PLEASE DO NOT OPERATE THE ACTUATOR BEFORE MOUNTING.
- 必ず基板上に実装してからアクチュエータを操作して下さい。
PLEASE OPERATE THE ACTUATOR AFTER MOUNTING ON THE SUBSTRATE.
- FPCについて
ABOUT FPC
補強フィルム材質はポリイミドを推奨します。ベースフィルムは25μmを推奨します。
接着剤は熱硬化接着剤を推奨します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。
RECOMMENDED STIFFENER MATERIAL: POLYIMIDE
RECOMMENDED BASE FILM THICKNESS: 25 MICROMETER
RECOMMENDED ADHESIVE: THERMOSETTING ADHESIVE
NOTE: PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

打抜き方向は導体側から補強板側を推奨致します。
導体部については軟銅箔35μmまたは50μmを推奨致します。
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
RECOMMENDED CONDUCTOR SPECIFICATION:
THICKNESS OF SOFT COPPER FOIL: 35MICROMETER OR 50 MICROMETER

- 平坦度は0.1以下
COPLANARITY TO BE 0.1 MAXIMUM



適合FPC推奨寸法

仕上がり厚さ : 0.2±0.03
APPLY FPC
RECOMMENDED DIM.
THICKNESS : 0.2±0.03

補強板: ポリイミド
REINFORCE BOARD: POLYIMIDE
熱硬化接着剤
THERMOSETTING ADHESIVE
ベースフィルム: ポリイミド (25μm)
BASE FILM: POLYIMIDE (25μm)
熱硬化接着剤
THERMOSETTING ADHESIVE
導体部: 銅箔 (35μm)
COPPER FOIL (35μm)
熱硬化接着剤
THERMOSETTING ADHESIVE
カバーレイ: ポリイミド (25μm)
COVER FILM: POLYIMIDE (25μm)

めっき: 金めっき (0.1μm以上)
下地: ニッケル (1-5μm)
PLATING: GOLD (0.1μm MIN.)
NICKEL UNDER (1-5μm)

FPC構成推奨仕様
STRUCTURE OF FPC

REVISED	EC NO. J2011-0598	DRWN:SHIRATA 2010/10/19	CHKD:KAKAHASHI 2010/10/19	APPR:KMORIKAWA 2010/10/25	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
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						30 OVER	± 0.3	APPROVED BY KMORIKAWA	DATE 2010/10/25	MOLEX MOLEX INCORPORATED	DOCUMENT NO. SD-502350-001	SHEET NO. 2 OF 2	
						ANGULAR ±3 °		MATERIAL NO. SEE CHART1					
					REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

